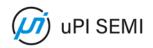


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P-Channel 30V Fast Switching MOSFET

General Description

The QM3017AM3 is a high performance trench P-channel MOSFET which utilizes extremely high cell density to provide low Rdson and gate charge characteristics. It is ideally suited to support most of Load switching and Motor applications .

The QM3017AM3 meets RoHS and Green Product requirements while supporting full function reliability.

Features

- ✓ Advanced high cell density Trench technology
- ✓ Super Low Gate Charge
- ✓ Excellent CdV/dt effect decline
- ✓ Green Device Available

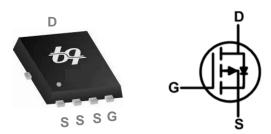
Product Summary

V _{DS}	R _{DS(ON)} max (V _{GS} =-10V)	I _D (Tc=25 °C)
-30V	7.9mΩ	-56A

Applications

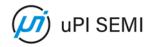
- ✓ Networking DC-DC Power System
- ✓ Load Switch

Pin Configuration



Ordering Information

Order Number	Package Type	Top Marking
QM3017AM3	PRPAK3X3	Pin 1 dot M 3 0 1 7 A M X X X X X X Date Code Assy Code Sequence Weekly Yearly



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-30	V
V _G S	Gate-Source Voltage	±25	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ -10V ¹	-56	Α
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ -10V ¹	-36	Α
ID@T _A =25°C	Continuous Drain Current, V _{GS} @ -10V ¹	-11.1	Α
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ -10V ¹	-8.9	Α
I _{DM}	Pulsed Drain Current ²	-112	Α
EAS	Single Pulse Avalanche Energy ³	172.9	mJ
I _{AS}	Avalanche Current	-58.8	Α
PD@Tc=25°C	Total Power Dissipation ⁴	43.4	W
P _D @T _A =25°C	Total Power Dissipation ⁴	1.67	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C

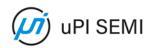
Thermal Data

Symbol	Parameter		Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹		75	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	1	2.88	°C/W



P-Channel Electrical Characteristics

P-Channel Electrical Characteristics: (T _J =25 °C, unless otherwise noted)						
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-30			V
△BV _{DSS} /△T _J	BVDSS Temperature Coefficient	Reference to 25°C , I _D =-1mA		-0.018		V/°C
Danier	Static Drain-Source	V _{GS} =-10V , I _D =-15A		6.3	7.9	0
R _{DS(ON)}	On-Resistance ²	V _{GS} =-4.5V , I _D =-10A		10	13	mΩ
V _{GS(th)}	Gate Threshold Voltage	\\ -\\ - 250\	-1.2	-1.4	-2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, I_D =-250uA		5.04		mV/°C
	Drain-Source Leakage Current	V _{DS} =-24V , V _{GS} =0V , T _J =25°C			-1	
I _{DSS}		V _{DS} =-24V , V _{GS} =0V , T _J =55°C			-5	- uA
Igss	Gate-Source Leakage Current	V _{GS} =±25V , V _{DS} =0V			±100	nA
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-10A		25		S
Qg	Total Gate Charge			30		
Qgs	Gate-Source Charge	V _{DS} =-15V , V _{GS} =-4.5V , I _D =-10A		10		nC
Q_{gd}	Gate-Drain Charge			10.4		
t _{d(on)}	Turn-On Delay Time			9.4		
t _r	Rise Time	V _{DS} =-15V , V _{GS} =-10V ,		10.2		
t _{d(off)}	Turn-Off Delay Time	$R_G=3.3\Omega$, $I_D=-10A$		117		ns
t _f	Fall Time			24		
Ciss	Input Capacitance			3448		
Coss	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		508		pF
C _{rss}	Reverse Transfer Capacitance			421		



Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =-25V , L=0.1mH , I _{AS} =-42A	88.2			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current 1,6	\/-=\/-=0\/			-56	Α
Іѕм	Pulsed Source Current ^{2,6}	$V_G=V_D=0V$, Force Current			-112	Α
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C			-1.2	V
t _{rr}	Reverse Recovery Time	I _F =-10A , di/dt=100A/μs ,		19.4		nS
Qrr	Reverse Recovery Charge	T _J =25°C		9.1		nC

Note:

- 1. Test data conducted with surface mount attachment to 1 inch², FR-4 board utilizing 2oz copper
- 2. Pulse Test. Pulse width \leq 300uS, duty cycle \leq 2%
- 3. EAS data is a maximum rating. The test condition is V_{DD} =-25V, V_{GS} =-10V,L=0.1mH
- 4. The power dissipation is limited by a 150°C maximum junction temperature
- 5. The Min. value is 100% EAS tested guarantee
- 6. The data is theoretically the same as I_D and I_{DM} . In real applications, it will be limited by total power



Typical Characteristics

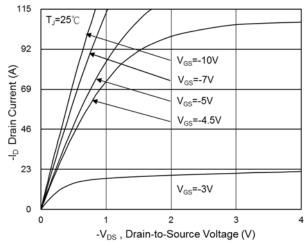


Fig.1: Typical Output Characteristics

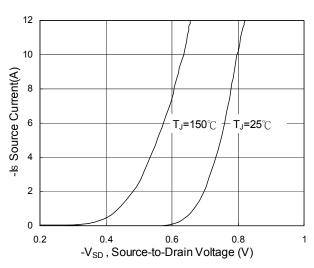


Fig.3: Forward Characteristics of Reverse

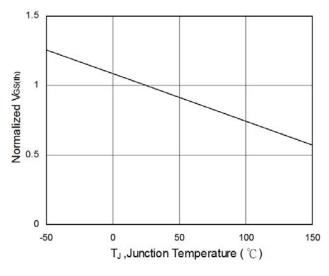


Fig.5: Normalized V_{GS(th)} vs. T_J

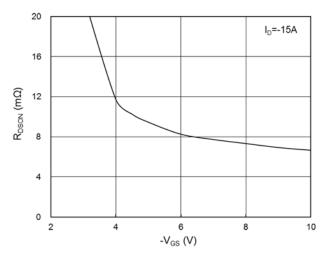


Fig.2: On-Resistance vs. Gate-Source

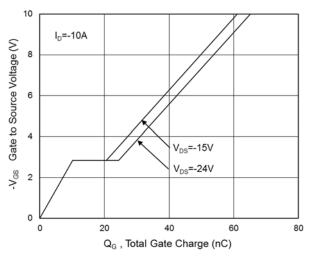


Fig.4: Gate-Charge Characteristics

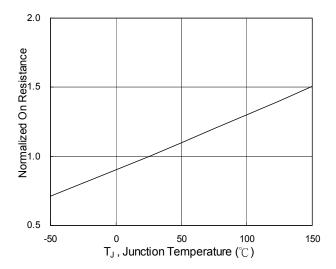
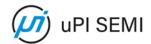
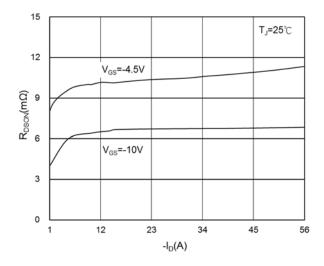


Fig.6: Normalized RDSON vs. TJ



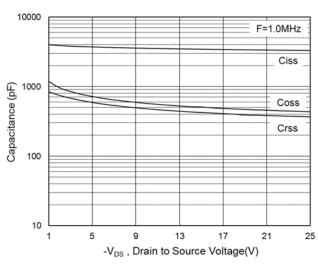


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Fig.7: Drain-Source On-State Resistance





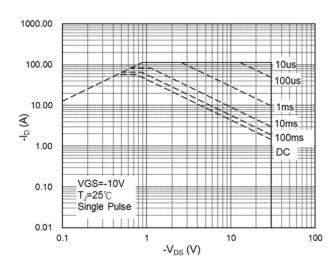


Fig.9: Capacitance

Fig.10: Safe Operating Area

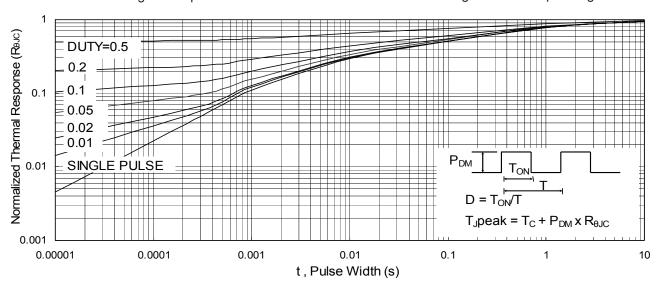
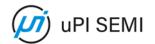


Fig.11: Normalized Maximum Transient Thermal Impedance



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